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KYZEN to Focus on AI Chip Reliability and Advanced Packaging at SEMICON Taiwan

NASHVILLE — August 2026 — KYZEN, the global leader in innovative environmentally responsible cleaning chemistries, will exhibit in Booth I2423 at SEMICON Taiwan from September 2-4, 2026, at TaiNEX Hall 1 and 2 in Taipei, Taiwan. KYZEN's team of experts will highlight cleaning technologies designed to address the increasingly complex requirements of advanced AI and semiconductor packaging processes.

As Artificial Intelligence (AI) applications continue to grow, semiconductor packaging technologies are undergoing significant transformation. Advanced packaging processes including CoWoS and CoPoS, together with heterogeneous integration, large die sizes, 3D stacking technologies and increasingly small gap spaces, are creating new challenges for effective cleaning.

Within these highly precise processes, residual flux can present a significant challenge to product reliability. Inadequate cleaning can contribute to electrochemical migration, leakage currents and component failure, making effective flux residue removal increasingly important as packaging complexity increases.

At SEMICON Taiwan, KYZEN will showcase its latest flux cleaning technologies and innovative cleaning solutions developed to support advanced AI processes and help manufacturers achieve high reliability standards.

For more than 35 years, KYZEN has developed cleaning chemistries and process solutions to help electronics manufacturers achieve reliable cleaning results while improving process efficiency. As advanced packaging architectures become increasingly complex, the company continues to apply this cleaning expertise to the evolving challenges presented by semiconductor manufacturing.

KYZEN will also use SEMICON Taiwan to formally announce Gary Liu as Sales Leader – North Asia, a position he assumed in late 2025. In his role, Liu is focused



on supporting KYZEN's continued growth within the region's semiconductor market and working closely with Regional Managers and R&D teams to accelerate customer evaluations and qualifications. With North Asia serving as a global center for semiconductor packaging R&D and high-volume manufacturing, the region represents an important part of KYZEN's continued semiconductor expansion.

"North Asia is a global center for semiconductor packaging R&D and high-volume manufacturing, spanning advanced packaging and IC substrates," said Liu. "With AI-driven growth accelerating demand for these technologies, the need for robust, high-yield process solutions is increasing rapidly. Close collaboration with our Regional Managers and R&D teams will be essential to accelerate qualifications and drive sustained success."

Visitors to SEMICON Taiwan are invited to meet KYZEN's cleaning experts at Booth I2423 to discuss the latest flux cleaning technologies and solutions for advanced AI and semiconductor packaging applications.

For more information, visit www.kyzen.com.

About KYZEN

KYZEN is a global leader in providing environmentally responsible, RoHS compliant precision cleaning chemistries for industries ranging from electronics and advanced packaging to metal finishing and aerospace applications. Since its founding in 1990, KYZEN's innovative cleaning technologies, scientific expertise and customer support have been repeatedly recognized with the industry's most prestigious awards. For more information, visit www.kyzen.com.